Express Mail Label No. EV 321 688 994 US

Figure 1A

110

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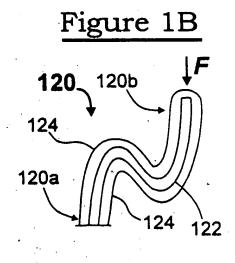


Figure 1C

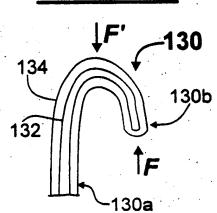


Figure 1D

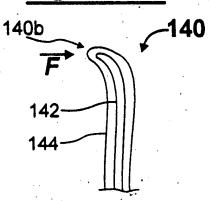
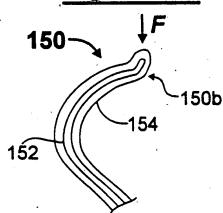
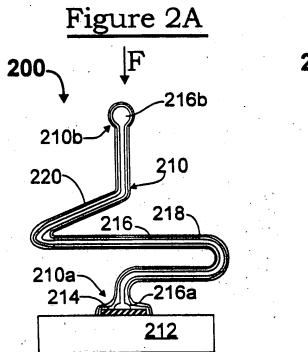
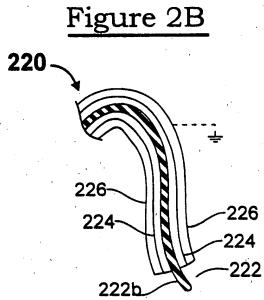
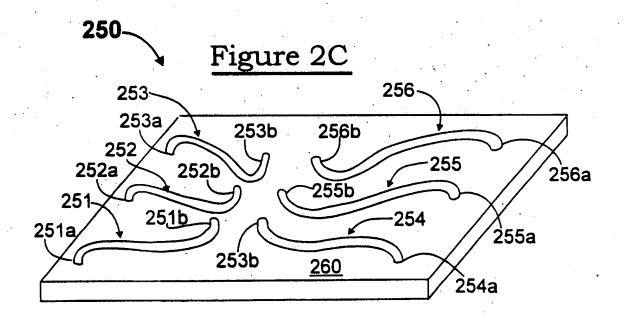


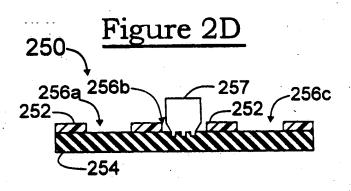
Figure 1E

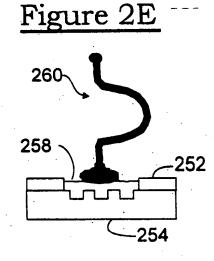


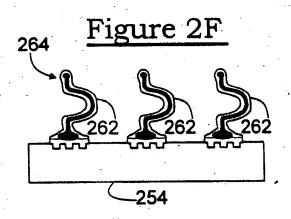












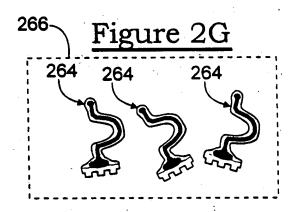


Figure 2H

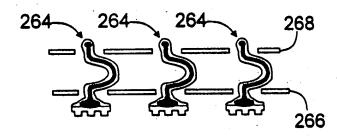
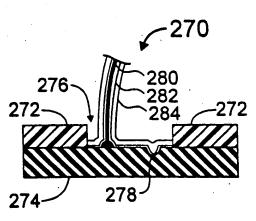
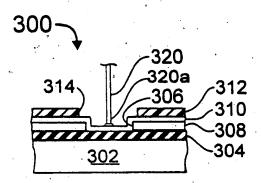


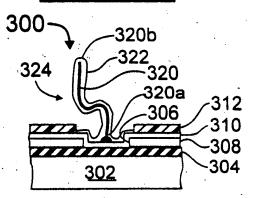
Figure 2I



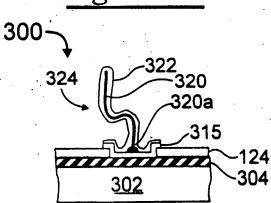
## Figure 3A



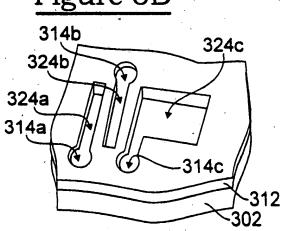
#### Figure 3B



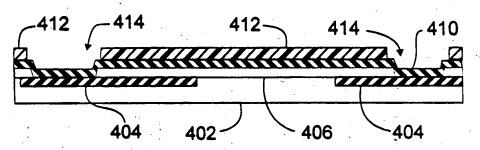
## Figure 3C



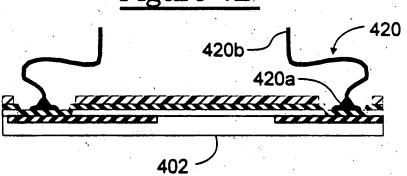
# Figure 3D



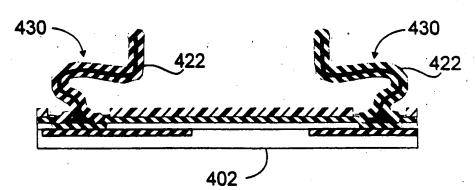
#### Figure 4A



#### Figure 4B



## Figure 4C



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#### Figure 4D

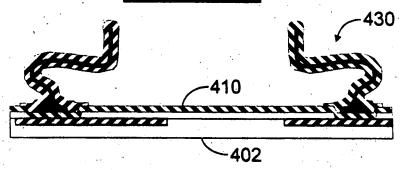


Figure 4E

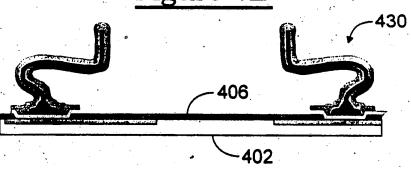


Figure 4F

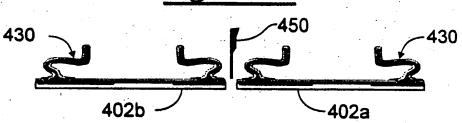
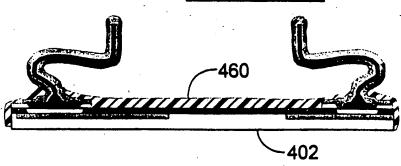


Figure 4G



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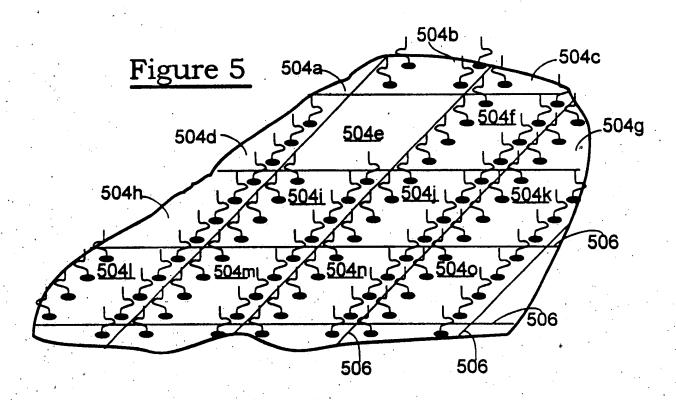
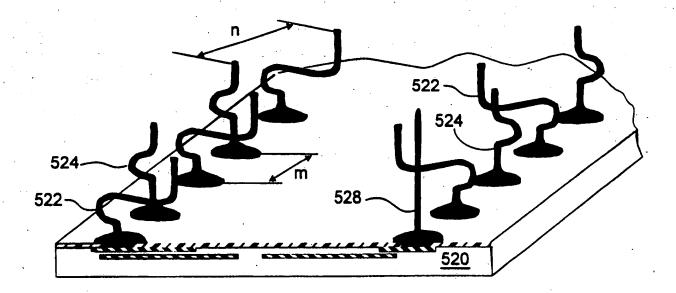
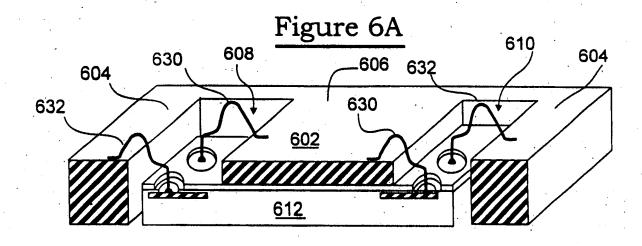
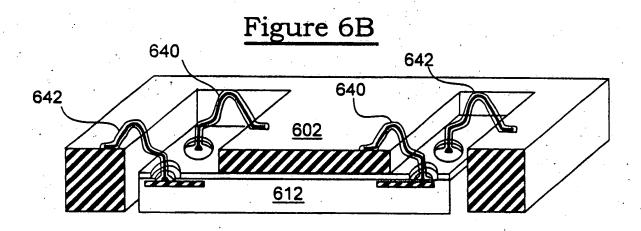
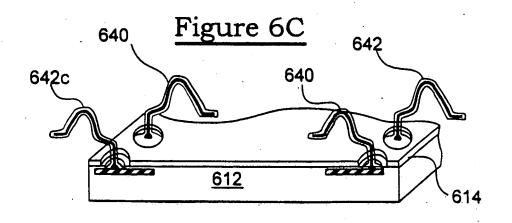


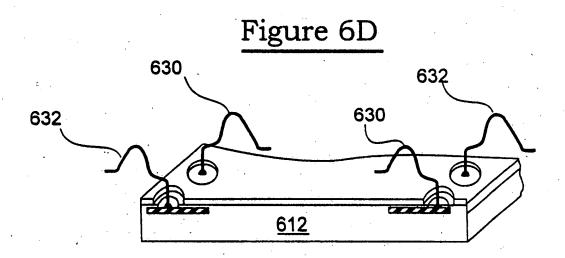
Figure 5A



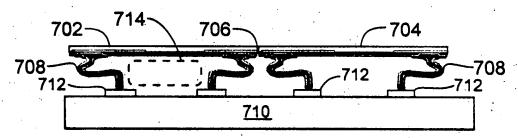




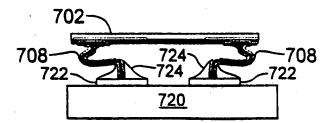


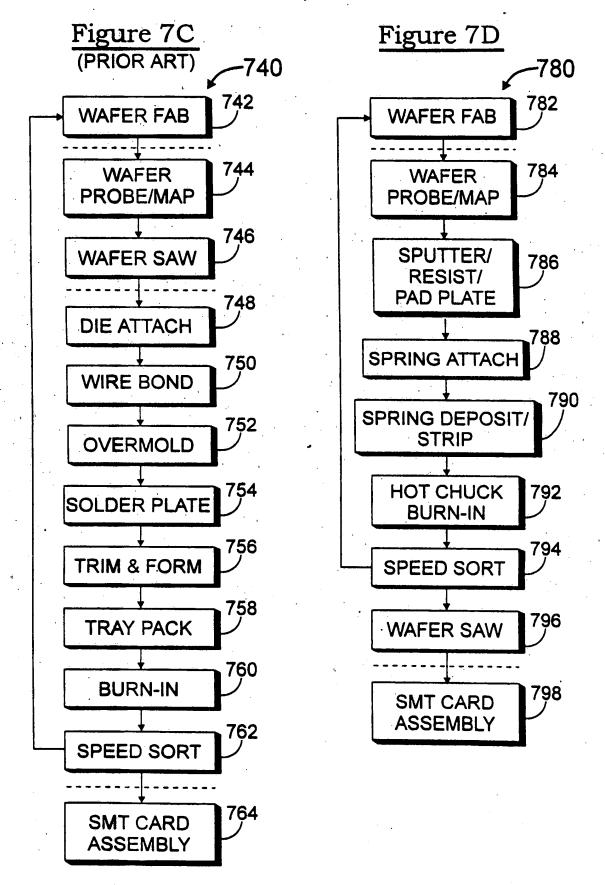


## Figure 7A



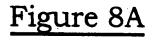
#### Figure 7B

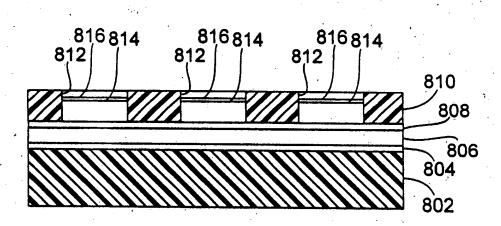




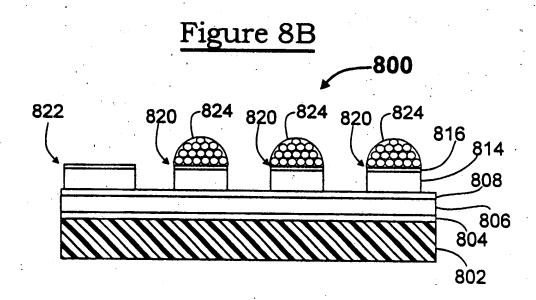
Mounting Spring Elements On Semiconductor Devices, and Wafer-Level Testing Methodology Eldridge et al.; P7D7C2-US Page 11/15

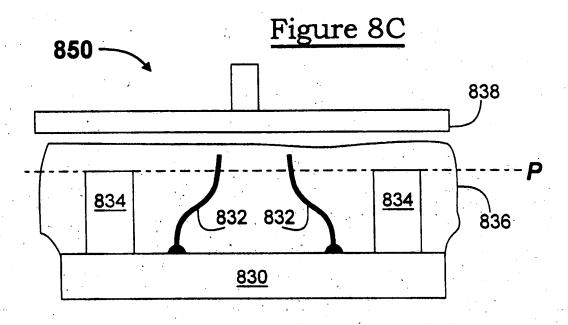
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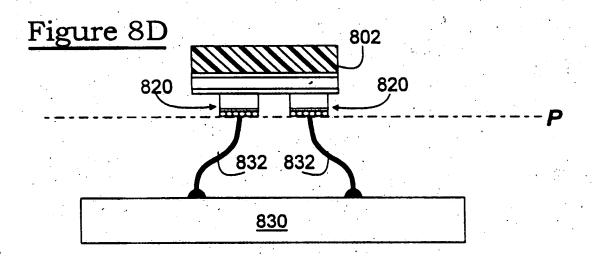


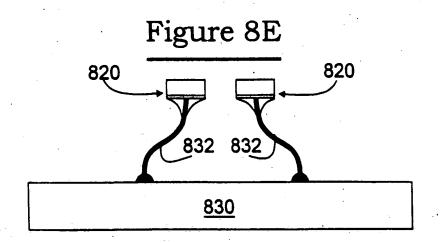


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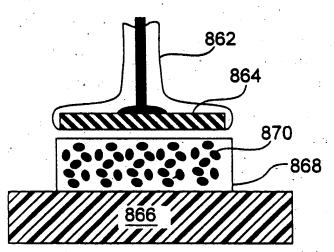


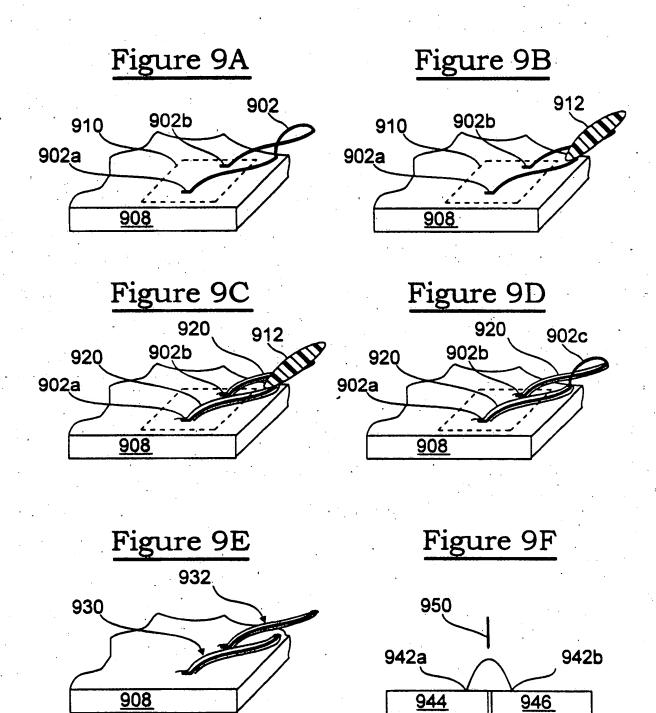


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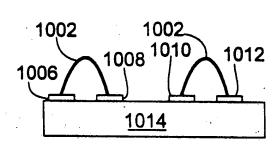
# Figure 8F





## Figure 10A

Figure 10B



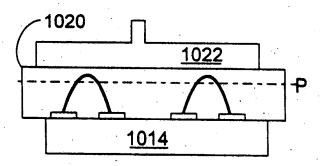


Figure 10C

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Figure 10D

